



ORIENT

Ph c le

P d c Da a Shee

Pa N be : OR-M302X/OR-M305X

C e : _____

Da e: _____

一级代理商：

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.frxelec.c



Fea

- (1) High...age be...ee i...a d (Vi :3750 V)
- (2) 4 i ... i ... d i e
- (3) High...ak ff- a ... :
- 302X... , 305X
- (4) High...f i e f ... d /d :
- 302X... / ,305X
- (5) Ta e...ackagi g.
- (6) Q e a ...e a e -40
- (7) S ... l
- ed(N .E32
- a ... ed(N .40 ... 3
- a ... ed (N .C ... 90 ... 1256)
- (8) I ... ce i h R HS, ... (C ... da d
- (9) M

De

...R-M302X,OR-M30...X c ... fa ... e c i g h iac, ... ll c led
 a gal ... a e ide i fa ede ... i g d de. The a e h ed i he SOP-4 ackage a d g a a ee
 i ... hick e .The ef e he ... he ei f cedi lai cla e ie ... f
 i e ... al afe ... a da d .

3. A ... ion Range

AC ... D i e	AC M ... S a e	S a i c ... e i ch
Ligh g C ... l	S le id/Val e C ... l	S lid S a e Rela
Te ... e a e C ... l		

4. F nc

5. Absolute Maximum Rating (Ta=25 °C)

	Parameter	Symbol	Rated Value	Unit
I	Forward Current	I_F	50	A
	Junction Temperature	T_J	125	°C
	Reverse Voltage	V_R	6	V
	Power Dissipation	P	100	W
	Off-State Thermal Voltage	V_{DRM}	400 (OR-M302X) 600 (OR-M305X)	V
O	Operating RMS Current	$I_{T(RMS)}$	100	A(RMS)
	Peak Reverse Surge Current (PW=1ms, 120°C)	I_{TSM}	1	A
	Junction Temperature	T_J	125	°C
	Collector Power Dissipation	P_C	300	W
	Base Power Dissipation	P	330	W
	Initial Voltage	V_i	3750	V
	Working Temperature	T	-40 ~ +110	°C
	Storage Temperature	T_g	-55 ~ +125	°C
2Soldering Temperature	T		°C	

Note:

*1 AC frequency, R.H.=40~60% R.H. In this table, items 1, 2 & 3 are half-bridge, and items 4, 6 are half-bridge.

*2 For 10 seconds



6. Electrical Characteristics at Ta=25°C

	Parameter	Symbol	Min	Typ	Max	Unit	Condition
I	Forward Voltage	V_F	---	1.2	1.6	V	$I_F=10\text{mA}$
	Reverse Current	I_R	---	---	5	μA	$V_R=6\text{V}$
	*1. Peak Blocking Current, Emitter Connected	I_{DRM}	---	10	100	μA	$V_{DRM} = \text{Rated } V_{DRM}$
O	Peak Off-State Voltage, Emitter Connected	V_{TM}	---	---	2.5	V	$I_{TM}=100\mu\text{A}$ Peak
	*2. Critical Rate of Rise of Off-State Voltage	dV/dt	---	10	---	V/μs	$V_i = 240\text{V}$
	OR-M302X		---	10	---		
	OR-M305X		---	800	---		

T b

Бс ' 2
5

∅

„Бс— б

OR-M302X

OR-M305X

E

OR-M302X/OR-M305X

OR-M302X/OR-M305X



7. O de Inf

Pa N mbe

OR M302X-W-Y-Z

O OR M305X-W-Y-Z

No e

X = Pa N e (0,1,2,3 4)

W = Ta e a eel i (TP TP1).

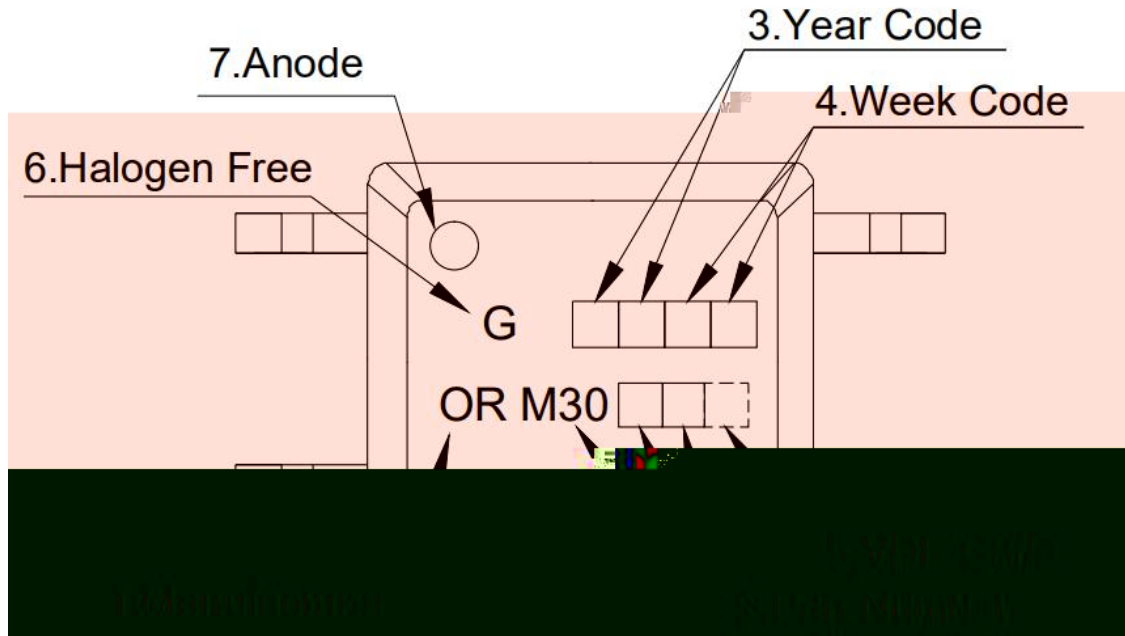
Y = V c def VDE afe (Thi i i ece a).

Z = G c def Hal ge fee.

* VDE C de ca be elec ed.

O ion	De c i ion	Packing an i
TP	S face lead f (1 file) + TP a e & eel i	3000 i e eel
TP1	S face lead f (1 file) + TP1 a e & eel i	3000 i e eel

8. Naming Rule



1. Manufacturer : ORIENT.

2. Part Number : M30 .

3. Year Code '21' or '2021' and .

4. Week Code 01 or the first week, 02 or the second week and .

5. VDE Code (Optional)

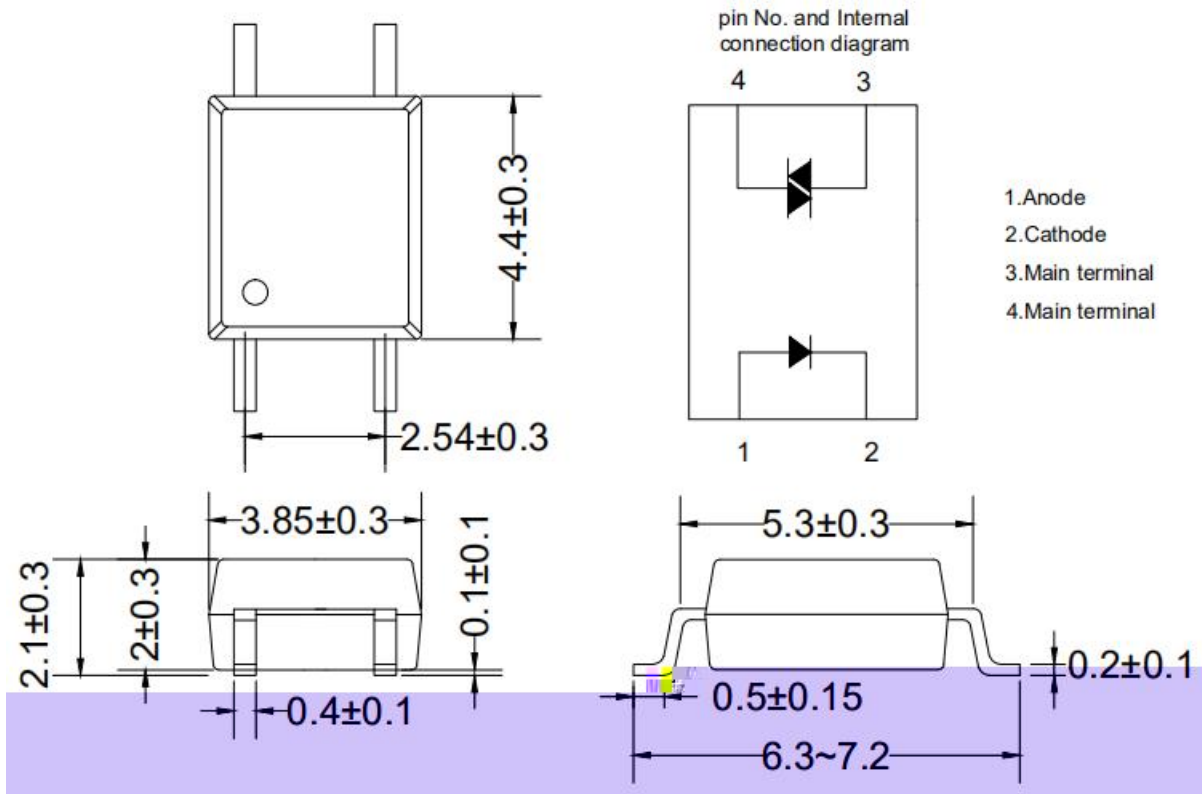
6. HFC Code G : Halogen Free.

7. Anode.

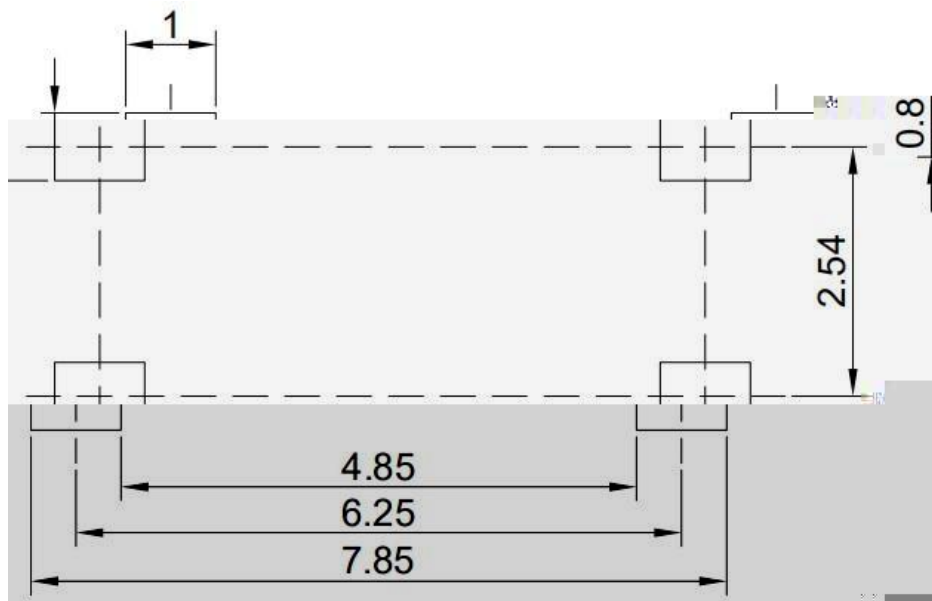
* VDE Code can be elected.

9. Package Dimension

OR-M30XX



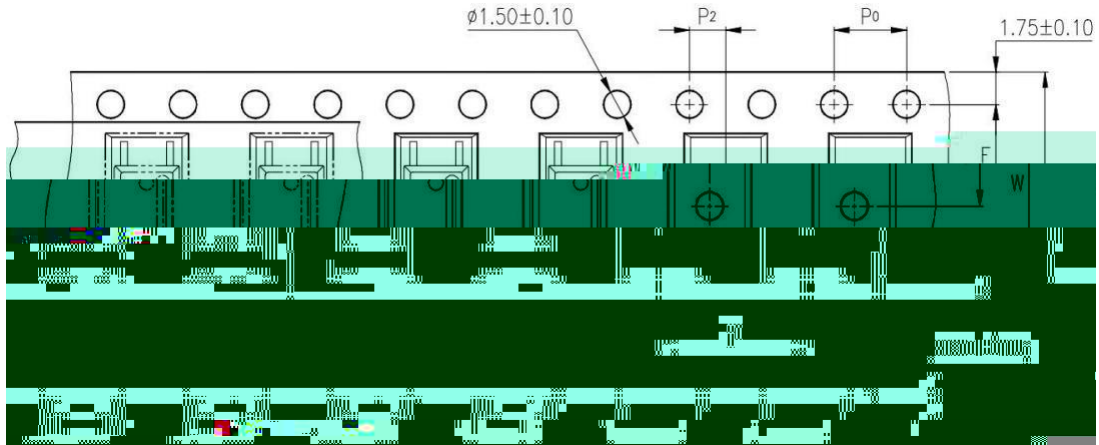
10. Recommended Foot Print Pattern (Mount Pad)



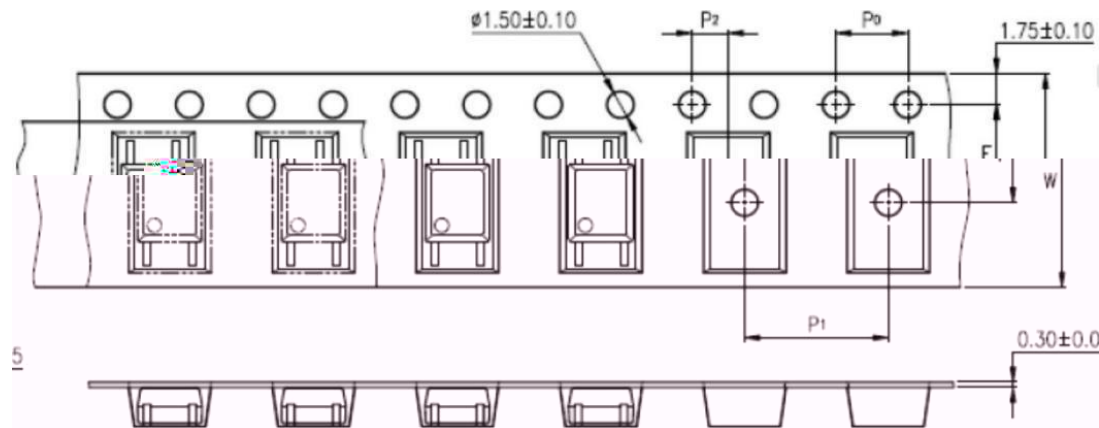
unit: mm

11. Taing Dimen ion

(1)OR-M30XX-TP



(2)OR-M30XX-TP1



De c i i	S	l	Di	i i	(i ch)
Ta e ide	W		12	0.3	0.472
Pi ch f cke h le	P0		4	0.1	0.157
Di a ce f c a	F		5.5	0.1	0.217
	P2		2	0.1	0.079
Di a ce c a	P1		8	0.1	0.315

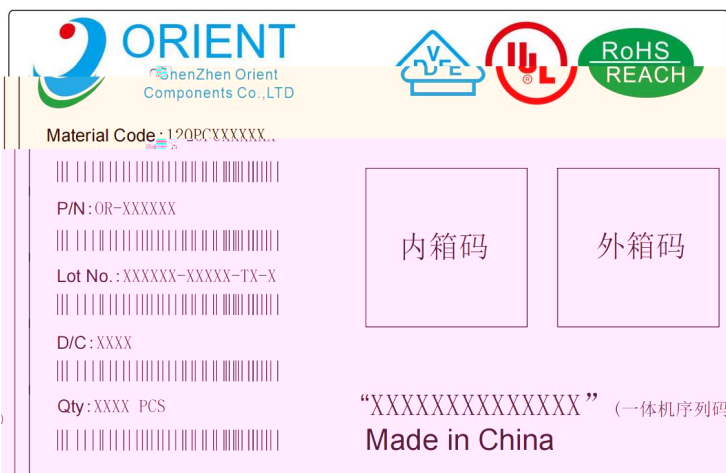
Package T e	TP/TP1
Q a i ie (c)	3000

12. Package Dimension

(1) Package dimension

Packing Information	
Packing	Reel
Tape Width	12mm
Quantity Reel	3,000 pcs
Small (inner) Dimension	345*345*45mm
Large (Outer) Dimension	480*360*360mm
Master Small	6,000 pcs
Master Large	60,000 pcs

(2) Packing Label Sample



Note

1. Material Code: Product ID.
2. P/N: Code with "O" de
If "i" is the specification.
3. Lot No.: Product data.
4. D/C: Product week.
5. Quantity: Packaging quantity.

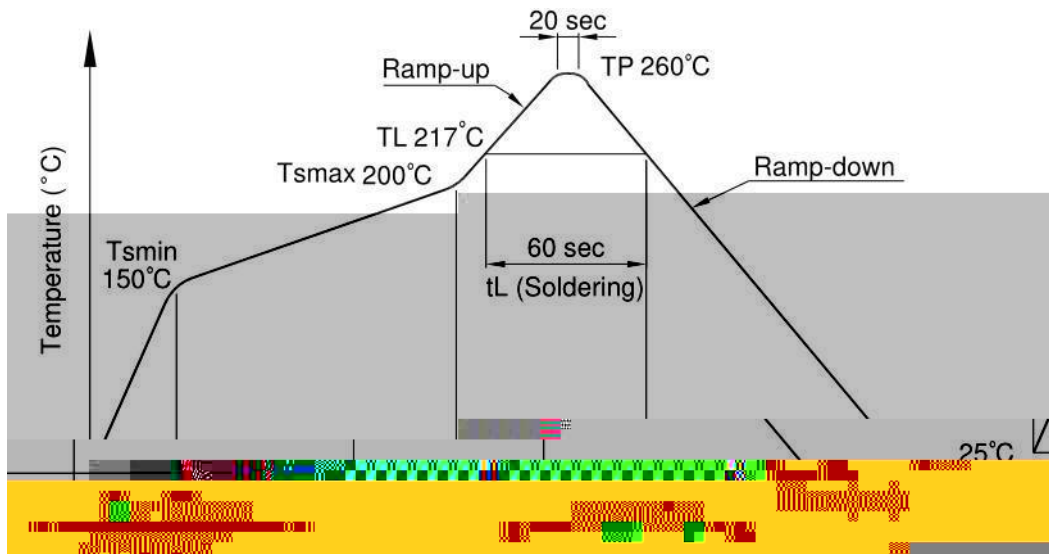


13. Temperature Profile Of Soldering

1 IR Refl... lde ig (JED...-STD-... c... lia)

O e i... lde ig efl... ec... ded i hi he c di i f e e a e a d i... file
h... bel... D... lde... e ha... e i...

Profile Item	Condition
- Temperature ()	150 C
- Temperature (Ma... S...)	200 C
- Time () ()	90 30 sec
S... e	
- Temperature (TL)	217 C
- Time (L)	60 sec
Peak Temperature	260 C
Peak Temperature i	20 sec
Ra... ae	3 C / sec
Ra...-d... ae f... eak e... e a e	3 6 C / sec
Refl... i	3





2 Wa e i g (JEDEC22A c lia)

O e i lde i gi ec ded i hi he c di i f e e a e.

Te e	260+0/-5 C
	10 ec
P eha e e e	5 140 C
P eha i	30 80 ec



3 Ha d lde i g b lde i gi

All i gle lead lde i gi e e i gle ce .O e i lde i gi ec ded.

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14. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward current vs Ambient temperature

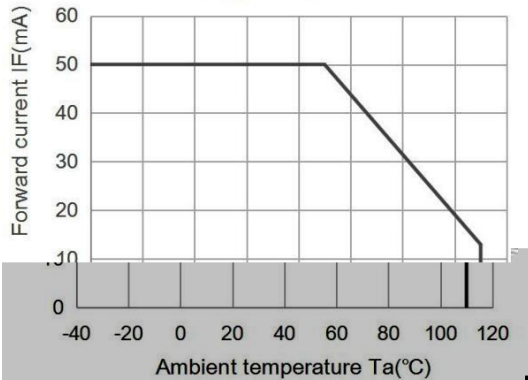


Fig.2 On-state current ITM (A) vs Ambient temperature

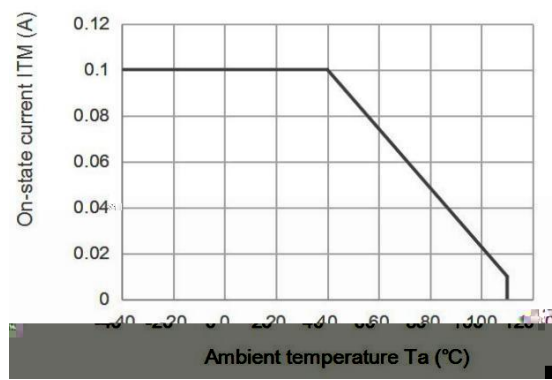


Fig.3 Minimum Trigger Current vs. Ambient temperature

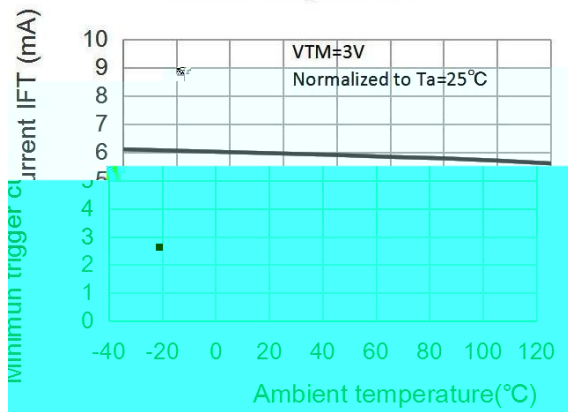


Fig.4 Forward current vs. Forward voltage

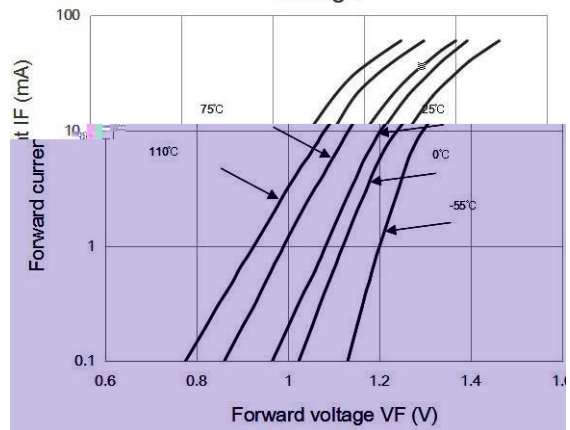


Fig.5 On-state voltage vs. Ambient temperature

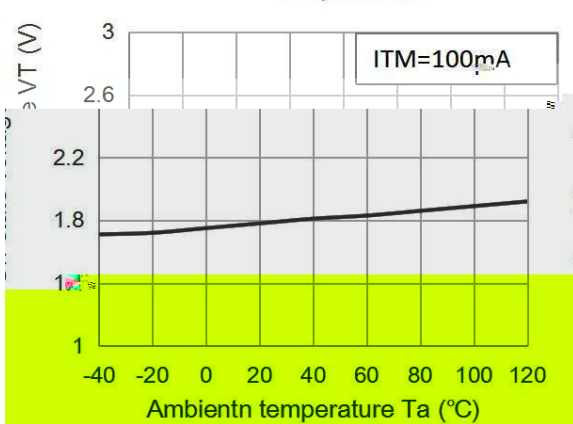


Fig.6 Holding current vs. Ambient temperature

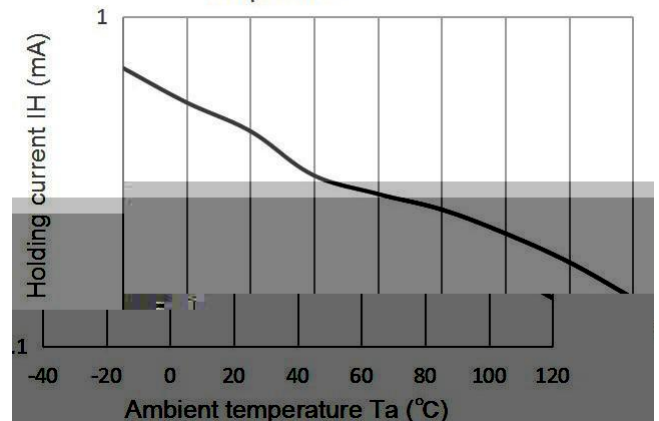


Fig.7 Repetitive peak off-state current

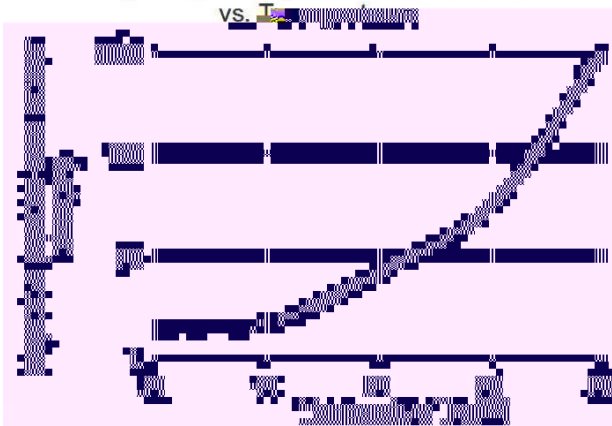


Fig.8 On-state current vs. On-state voltage

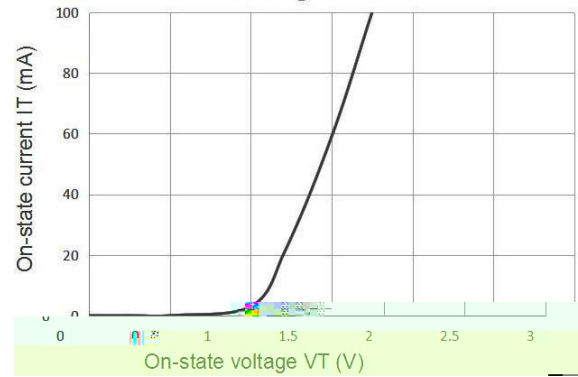


Fig9. Basic On-state Current Measurement /High Power Thyristor Diode Circuit

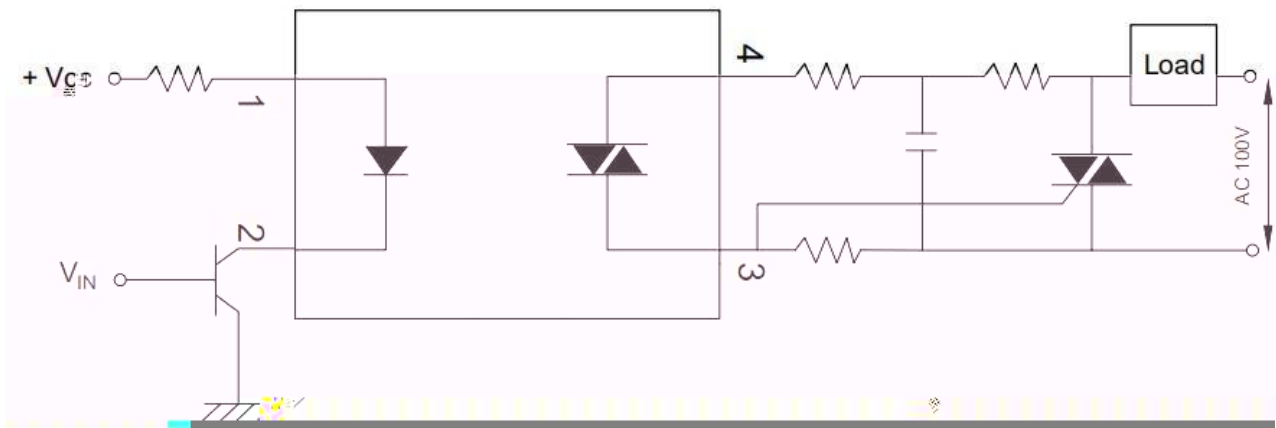
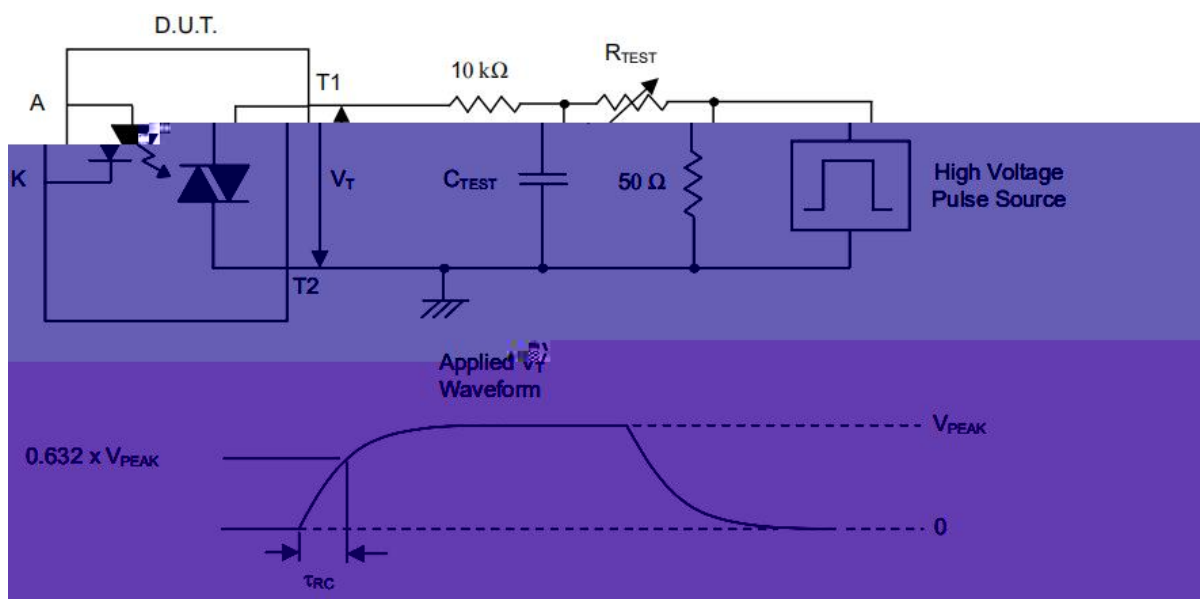


Fig10. Standard Test Circuit & Waveform



Measurement Method

